

Microchip**Filter specification****TFS 360P****1/5****Measurement condition**

Ambient temperature T_A :	23	°C
Input power level:	0	dBm
Terminating impedance: *		
Input:	188 Ω	-8.7 pF
Output:	234 Ω	-7.0 pF

Characteristics

Remark:

The reference level for the relative attenuation a_{rel} of the TFS 360P is the minimum of the pass band attenuation. This value is defined as the insertion loss a_e . The nominal frequency f_N is fixed at 360 MHz without any tolerance. The values of relative attenuation a_{rel} are guaranteed over the whole operating temperature range. The frequency shift of the filter within the operating temperature range is included in the production tolerance scheme.

D a t a		typ. value	tolerance / limit
Insertion loss (reference level)	a_e	10.1 dB	max. 12.8 dB
Nominal frequency	f_N		360.0 MHz
Passband	PB		f_N \pm 30 MHz
Pass band ripple	p-p	0.7 dB	max. 1.2 dB
Relative attenuation	a_{rel}		
f_N MHz ... $f_N \pm 30$ MHz		0.7 dB	max. 1.2 dB
$f_N - 320$ MHz ... $f_N - 250$ MHz		80 dB	min. 50 dB
$f_N - 250$ MHz ... $f_N - 137$ MHz		65 dB	min. 40 dB
$f_N - 137$ MHz ... $f_N - 77$ MHz		55 dB	min. 35 dB
$f_N + 94$ MHz ... $f_N + 109$ MHz		54 dB	min. 40 dB
$f_N + 109$ MHz ... $f_N + 214$ MHz		55 dB	min. 45 dB
$f_N + 214$ MHz ... $f_N + 274$ MHz		54 dB	min. 50 dB
Average group delay within PB		0.33 μ s	max. 0.35 μ s
Group delay ripple within PB		23 ns	max. 60 ns
Time sidelobe suppression within 1... 500μs		42 dB	min. 32 dB
Return loss within PB		13 dB	min. 9.5 dB
IIP3 ***		47 dBm	min. 40 dBm
Input power			max. 10 dBm
Operating temperature range	OTR		- 40 °C ... + 85 °C
Storage temperature range			- 55 °C ... + 125 °C
Temperature coefficient of frequency	TC_f **	-94 ppm/K	-

*) The terminating impedances depend on parasitics and q-values of matching elements and the board used, and are to be understood as reference values only. Should there be additional questions do not hesitate to ask for an application note or contact our design team.

**) $\Delta f = TC_f(T - T_A)f_N$

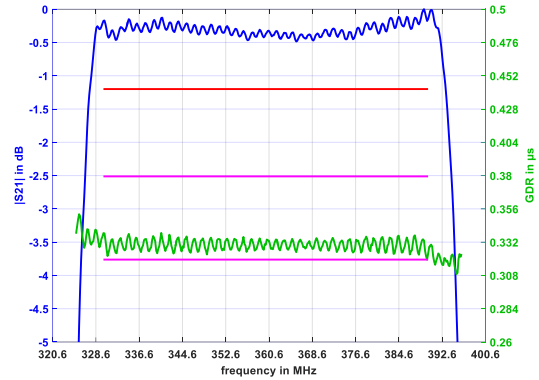
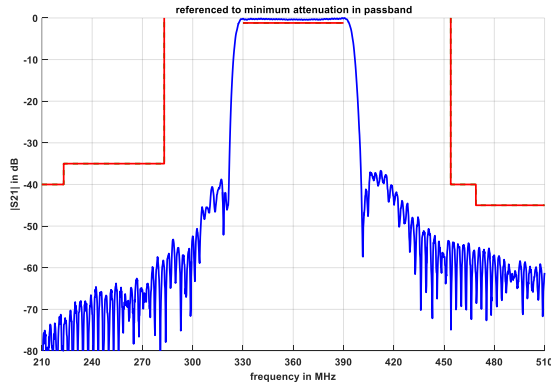
***) $f_{in1} = 357.5$ MHz; $f_{in2} = 362.5$ MHz; $P_{in} = 0$ dBm; $f_{measurement} = 352.5$ MHz

Generated:**Checked / Approved:**

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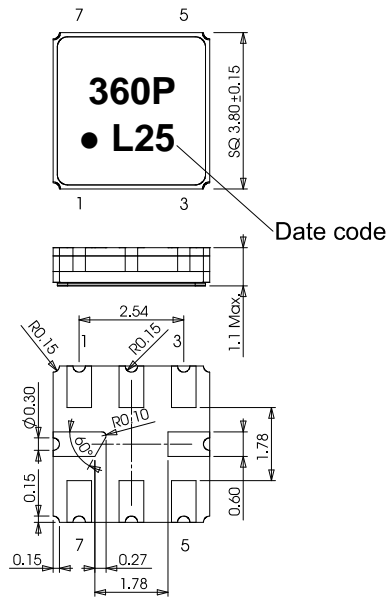
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Filter characteristic



Construction and pin connection

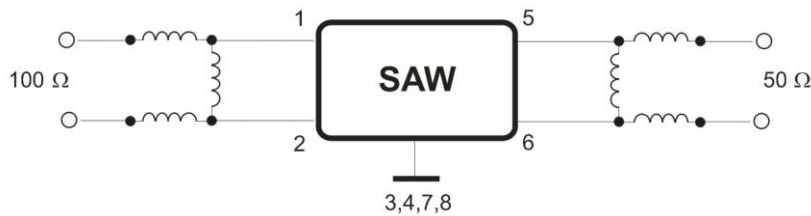
(All dimensions in mm)



- 1 Input
- 2 Input
- 3 Ground
- 4 Ground
- 5 Output
- 6 Output
- 7 Ground
- 8 Ground

Date code: Year + week
 L 2019
 M 2020
 N 2021
 ...

Test circuit



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Stability characteristics, reliability

After the following tests the filter shall meet the whole specification:

1. Shock: 500 g, 1 ms, half sine wave, 3 shocks each plane;
DIN IEC 60068 T2 - 27
2. Vibration: 10 Hz to 2000 Hz, 0.35 mm or 5 g respectively, 1 octave per min, 10 cycles per plane, 3 planes; DIN IEC 60068 T2 - 6
3. Change of temperature: -55 °C to 125 °C / 15 min. each / 100 cycles
DIN IEC 60068 part 2 – 14 Test N
4. Resistance to solder heat (reflow): reflow possible: three times max.;
for temperature conditions refer to the attached "Air reflow temperature conditions" on page 4;
5. SAW devices are Electrostatic Discharge (ESD) sensitive devices.

This filter is RoHS compliant (2011/65/EU)

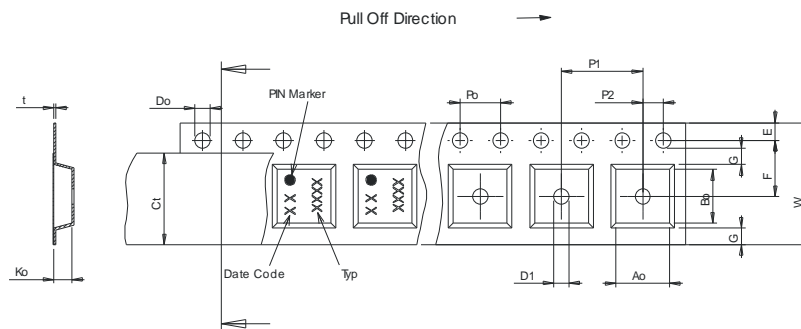
Packing

Tape & Reel: IEC 286 – 3, with exception of value for N and minimum bending radius;
tape type II, embossed carrier tape with top cover tape on the upper side;

reel of empty components at start:	min. 300 mm
reel of empty components at start including leader:	min. 500 mm
trailer:	min. 300 mm

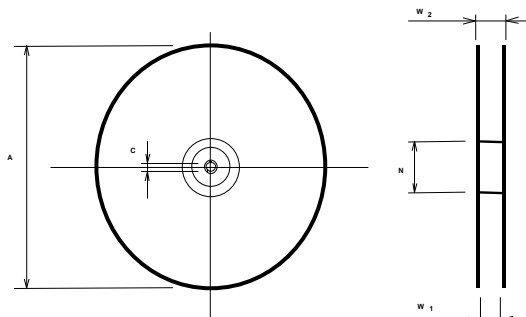
Tape (all dimensions in mm)

- W : 12.00 ±0.3
- Po : 4.00 ±0.1
- Do : 1.50 +0.1/-0
- E : 1.75 ±0.1
- F : 5.50 ±0.05
- G(min) : 0.75
- P2 : 2.00 ±0.05
- P1 : 8.00 ±0.1
- D1(min) : 1.50
- Ao : 4.30 ±0.1
- Bo : 4.30 ±0.1
- Ct : 9.2 ±0.1
- Ko : 1.80 ±0.1
- t : 0.30 ±0.05



Reel (all dimensions in mm)

- A : 330 or 180
- W1 : 16.4 +2/-0
- W2(max) : 22.40
- N(min) : 50.00
- C : 13.0 +0.5/-0.2



The minimum bending radius is 45 mm.

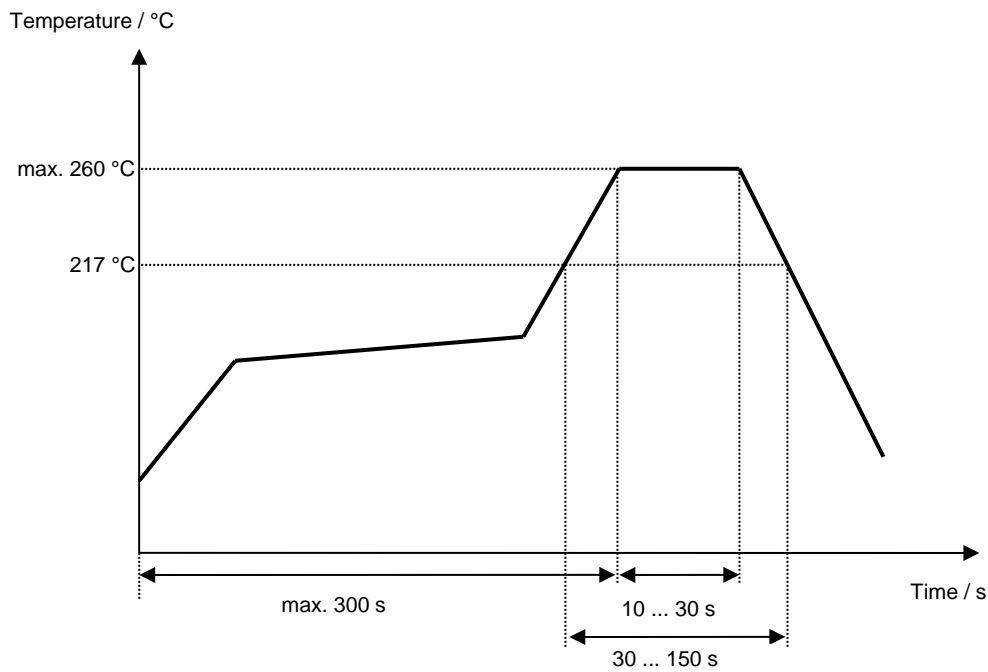
Air reflow temperature conditions

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Conditions	Exposure
Average ramp-up rate (30 °C to 217 °C)	less than 3 °C / second
> 100 °C	between 300 and 600 seconds
> 150 °C	between 240 and 500 seconds
> 217 °C	between 30 and 150 seconds
Peak temperature	max. 260 °C
Time within 5 °C of actual peak temperature	between 10 and 30 seconds
Cool-down rate (Peak to 50 °C)	less than 6 °C / second
Time from 30 °C to Peak temperature	no greater than 300 seconds

Chip-mount air reflow profile



Microchip**Filter specification****TFS 360P****5/5**

History

Version	Reason of Changes	Name	Date
1.0	- Generation of development specification.	Jaffer	28.02.2019
1.1	- Request to change package from 7x5mm ² to 3.8x3.8mm ² and input drive imp. from 200Ω to 100 Ω.	Jaffer	28.03.2019
1.2	- Add plots, typ. values and move to filter spec.	Jaffer	18.10.2019
1.3	- Update IIP3 nomenclature.	Jaffer	22.10.2019